

< L/S band internally matched power GaAs FET >

# MGFS52BN2122A

2.1 – 2.2 GHz BAND / 160W

## DESCRIPTION

The MGFS52BN2122A is a 160W push-pull type GaAs power FET especially designed for use in 2.1 – 2.2GHz band amplifiers. The hermetically sealed metal-ceramic package guarantees high reliability.

## FEATURES

Push-pull configuration

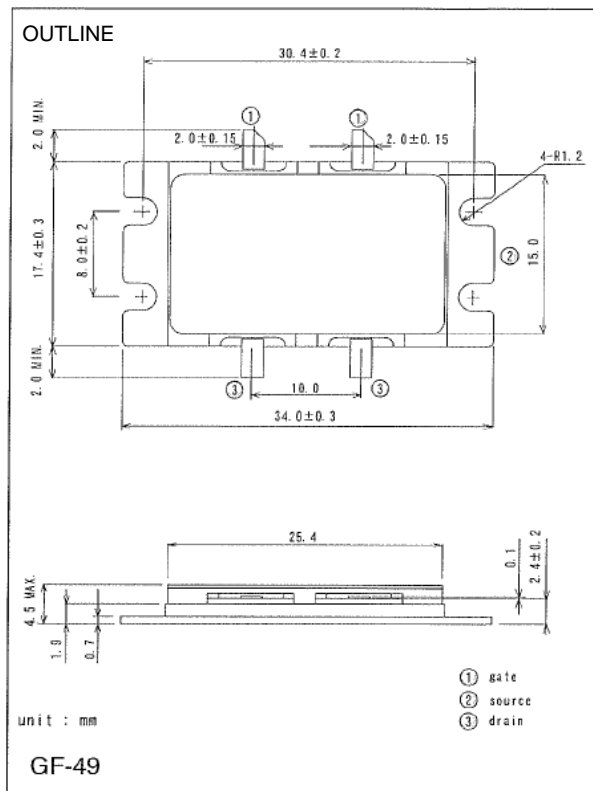
- High output power  
Pout=160W (TYP.) @f=2.17GHz
- High power gain  
GLP=12.0dB (TYP.) @f=2.17GHz
- High power added efficiency  
P.A.E.=48% (TYP.) @f=2.17GHz

## APPLICATION

- 2.1-2.2GHz band power amplifier for W-CDMA Base Station

## QUALITY

- IG



## RECOMMENDED BIAS CONDITIONS

- VDS=12V • ID=4.0A • RG=5ohm for each gate

## Absolute maximum ratings (Ta=25°C)

Symbol	Parameter	Ratings	Unit
VGDO	Gate to drain breakdown voltage	-20	V
VGSO	Gate to source breakdown voltage	-10	V
PT *1	Total power dissipation	187.5	W
Tch	Channel temperature	175	°C
Tstg	Storage temperature	-65 to +175	°C

\*1 : Tc=25°C

## Keep Safety first in your circuit designs!

Mitsubishi Electric Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage. Remember to give due consideration to safety when making your circuit designs, with appropriate measure such as (i) placement of substitutive, auxiliary circuits, (ii) use of non-flammable material or (iii) prevention against any malfunction or mishap.

## Electrical characteristics (Ta=25°C)

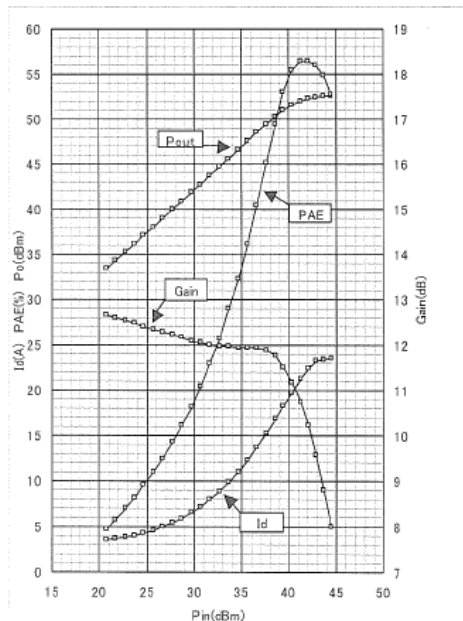
Symbol	Parameter	Test conditions	Limits			Unit
			Min.	Typ.	Max.	
GLP	Linear Power Gain	VDS=12V, ID(RF off)=4.0A, f=2.17GHz Pin=32dBm	11	12	-	dB
Pout	Output Power	VDS=12V, ID(RF off)=4.0A, f=2.17GHz Pin=43dBm	50.8	51.8	-	dBm
ID	Drain current	Pin=43dBm	-	23	30	A
P.A.E.	Power added efficiency		-	48	-	%
Rth(ch-c) *2	Thermal resistance	delta Vf method	-	0.55	0.8	°C/W

\*2 : Channel-case

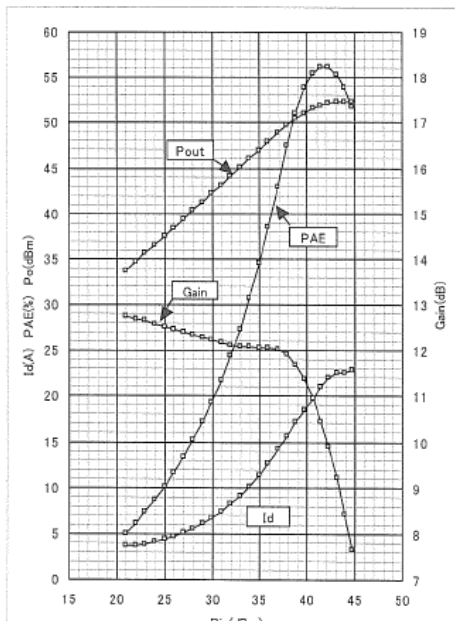
## MGFS52BN2122A TYPICAL CHARACTERISTICS

$P_{out}$  ,  $I_d$  , PAE , GAIN ,  $\Delta$  GAIN ,  $\Delta$  PHASE vs.  $P_{in}$  (CW 1-tone)

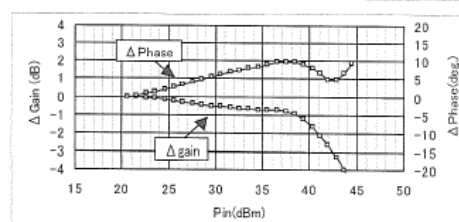
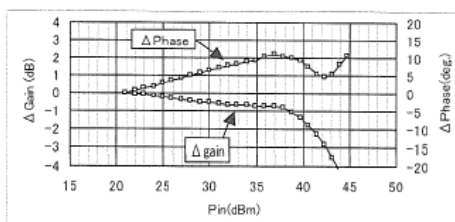
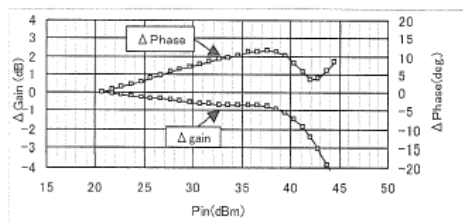
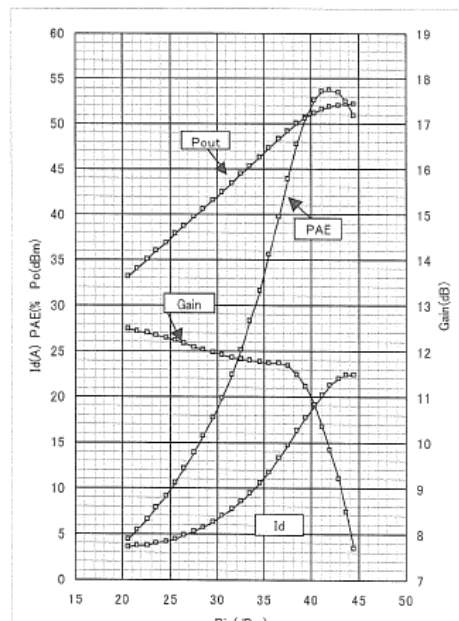
f=2.11GHz



f=2.14GHz



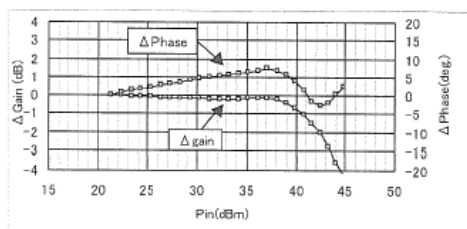
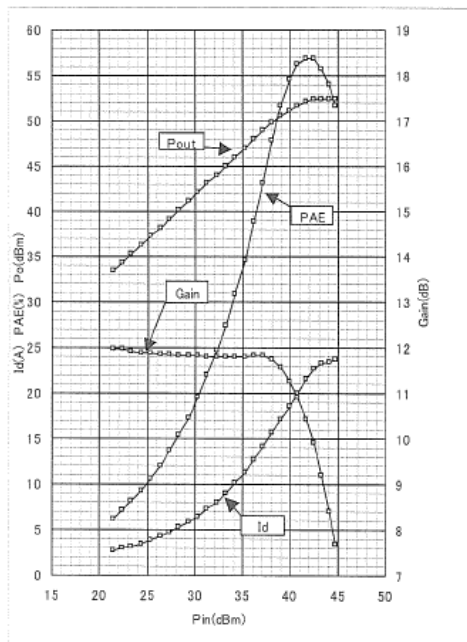
f=2.17GHz



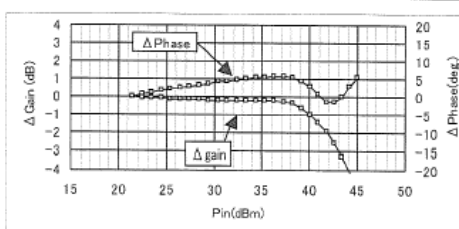
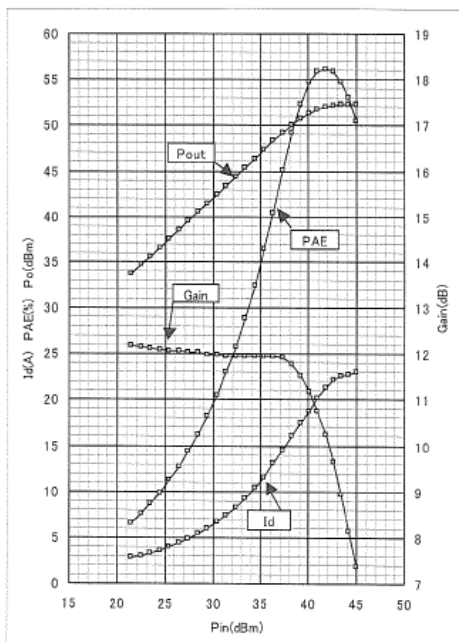
Test Condition :  $V_{ds}=12V, I_{dq}=4A, T_a=25deg.C$

**Pout , Id , PAE , GAIN ,  $\Delta$  GAIN ,  $\Delta$  PHASE vs. Pin (CW 1-tone)**

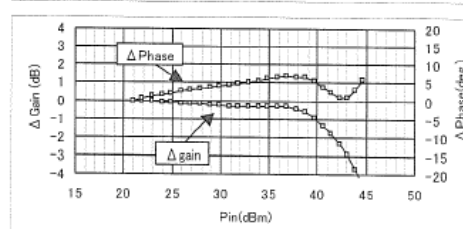
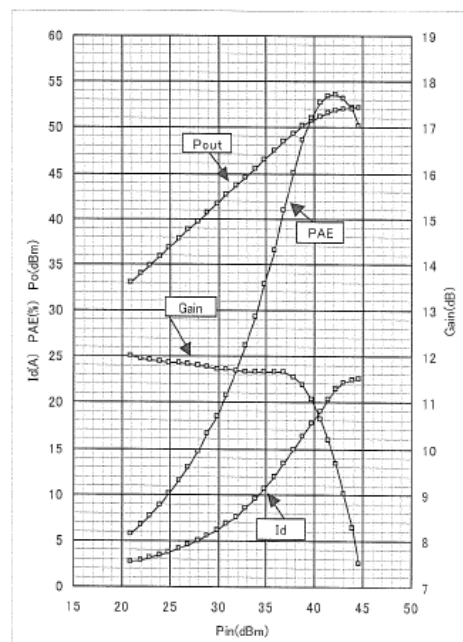
**f=2.11GHz**



**f=2.14GHz**



**f=2.17GHz**



Test Condition : Vds=12V, Idq=2A, Ta=25deg.C

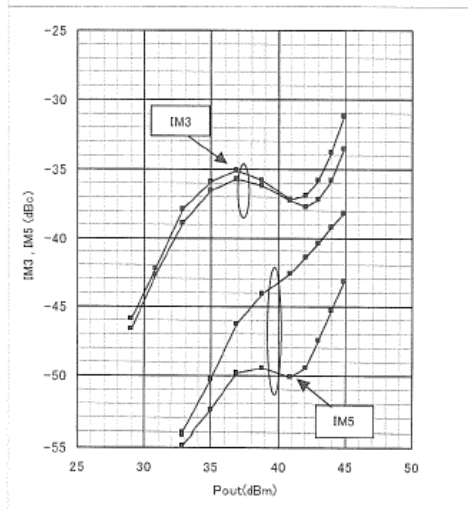
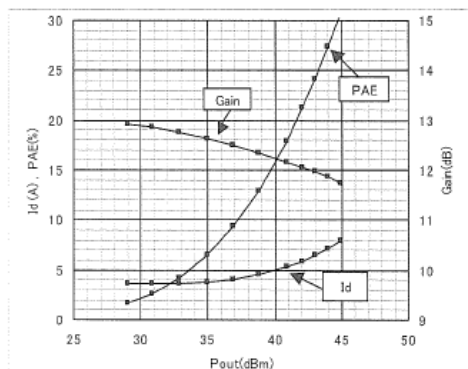
# MGFS52BN2122A

2.1 – 2.2 GHz BAND / 160W

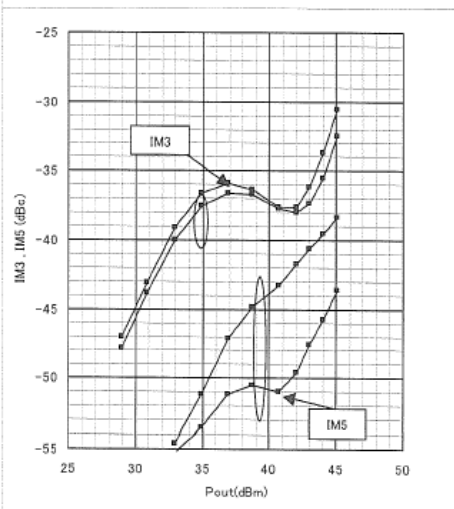
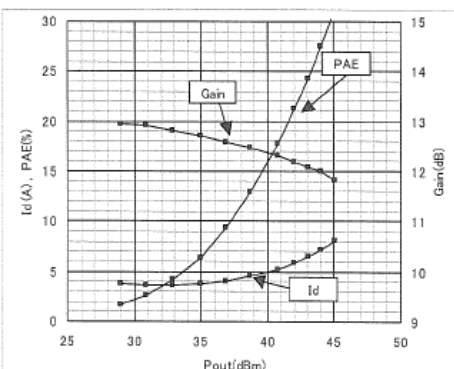
IM3 , IM5 , Id , PAE , GAIN vs. Pout

(W-CDMA signal , 2-tone 3GPP test model 1 w/64DPCH)

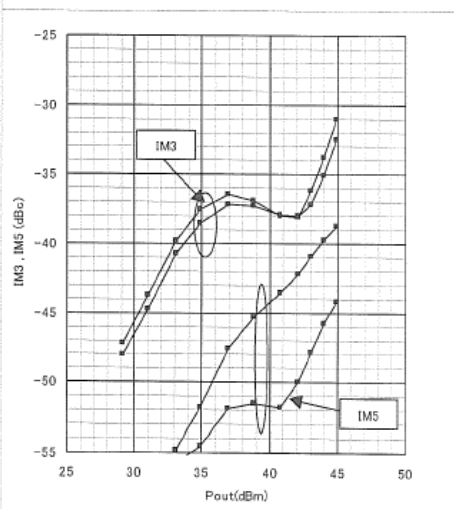
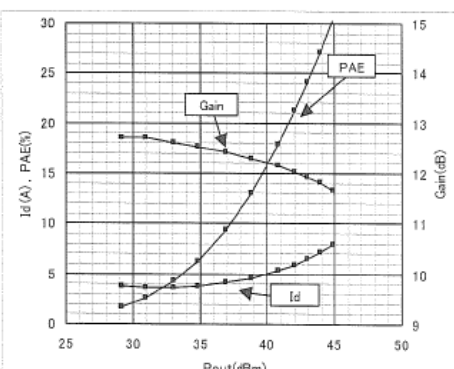
f=2.11GHz



f=2.14GHz



f=2.17GHz



Test Condition : Vds=12V, Idq=4A, Ta=25deg.C

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2.1 – 2.2 GHz BAND / 160W

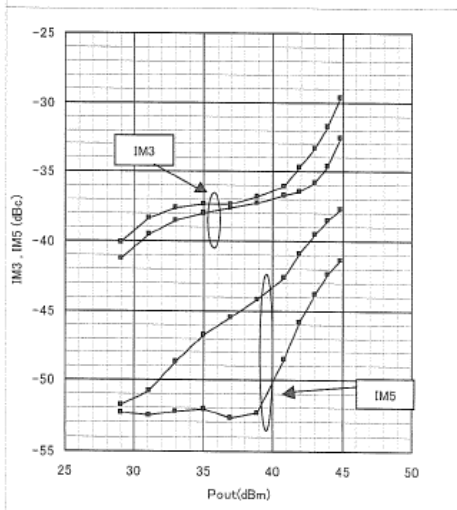
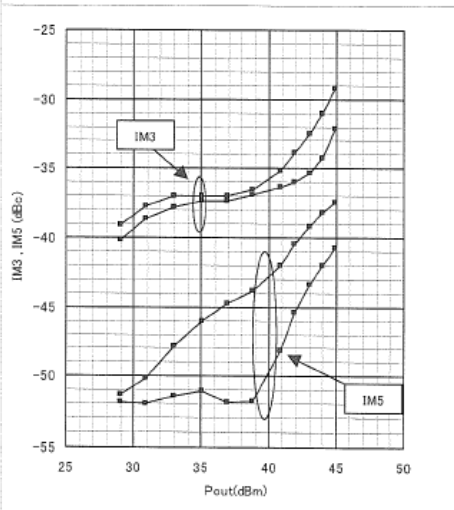
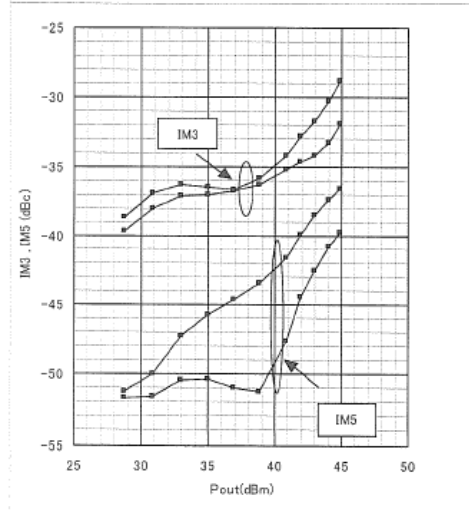
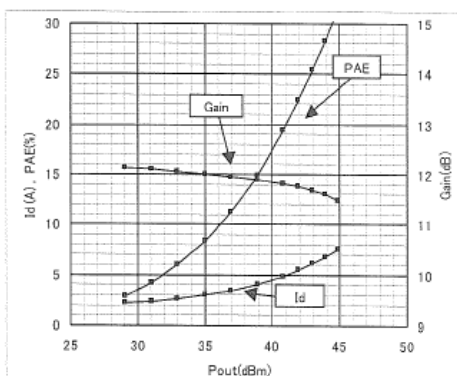
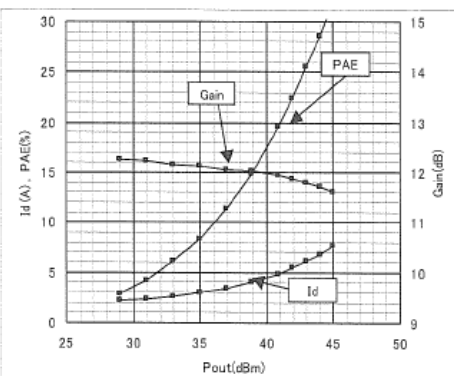
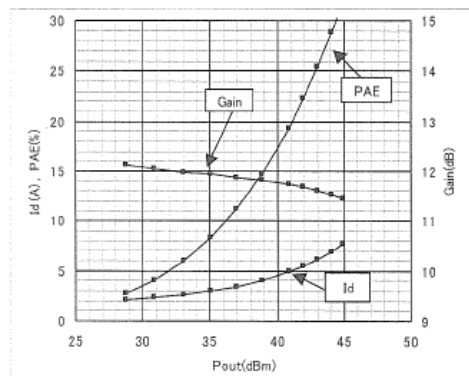
IM3 , IM5 , Id , PAE , GAIN vs. Pout

(W-CDMA signal , 2-tone 3GPP test model 1 w/64DPCH)

f=2.11GHz

f=2.14GHz

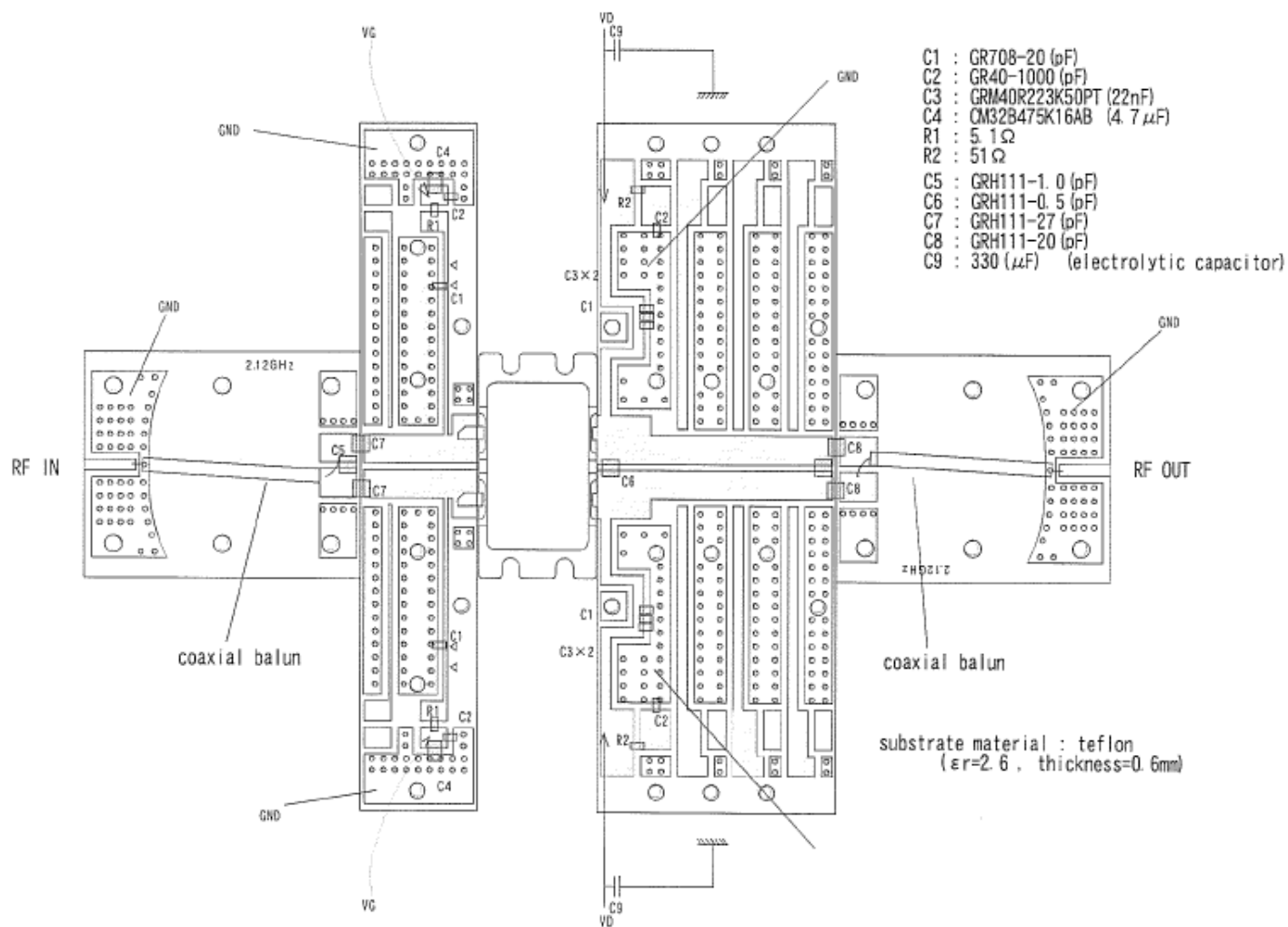
f=2.17GHz



Test Condition : Vds=12V, Idq=2A, Ta=25deg.C

**MGFS52BN2122A**

# MGFS52BN2122A RF TEST FIXTURE

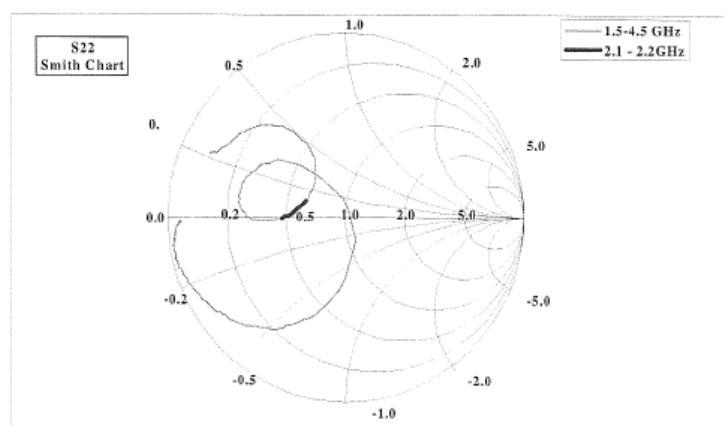
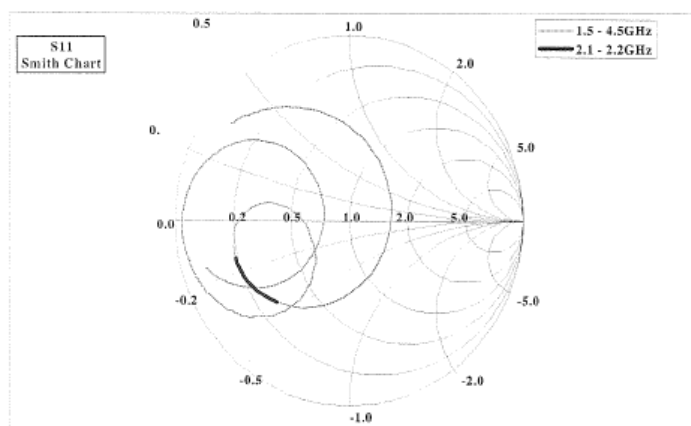


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## MGFS52BN2122A

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**MGFS52BN2122A S-parameters**( Ta=25deg.C , VDS=12(V),IDS=2.0(A) for one side FET )



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